AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-13 (canceled).

Claim 14 (currently amended): A manufacturing method for a laminated ceramic electronic component, comprising the steps of:

screen printing ~~an internal~~ a coil conductor pattern having a first land at one end of the ~~internal~~ coil conductor pattern and a second land at the other end of the ~~internal~~ coil conductor pattern on the surface of a ceramic sheet having a hole for a via hole formed therein by using a conductive material such that the first land covers the hole for via hole;

simultaneously filling the conductive material in the hole for the via hole during the step of screen printing the coil conductor pattern; and

laminating a plurality of ceramic sheets such that the first land in one of the plurality of ceramic sheets is electrically connected to the second land in another of the plurality of ceramic sheets through the via hole formed in the one of the plurality of ceramic sheets to obtain a laminate; wherein

an area of the via hole is less than an area of the first land and an area of the second land; and

the area of the second land is greater than the area of the first land.

Claim 15 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the second land extends from a projection plane of the first land to a projection plane of the ~~internal~~ coil conductor pattern.

Claim 16 (previously presented): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the area of the second land is about 1.10 to about 2.25 times as wide as the area of the first land.

Claim 17 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim 14, wherein the ~~internal~~ coil conductor pattern is printed on a ceramic sheet having the hole for the via hole formed therein and the hole for the via hole is filled with a conductive material, without providing a carrier film on a back surface of the ceramic sheet.

Claim 18 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim 14, further comprising the step of:

arranging the ~~internal~~ coil conductors on the plurality of ceramic sheets so as to define a spiral coil.

Claim 19 (previously presented): The manufacturing method for a laminated ceramic electronic component according to Claim 18, wherein terminal ends of the spiral coil define lead-out electrodes.

Claim 20 (currently amended): The manufacturing method for a laminated ceramic electronic component according to Claim 14, further comprising the steps of:

providing two additional ceramic sheets which do not include any ~~internal~~ coil conductors printed therein;

disposing one of the two additional ceramic sheets on an upper surface of the laminate; and

disposing the other of the two additional ceramic sheets on a lower surface of the laminate.

Claim 21 (canceled).